

规格书编号：

SPEC NO：

产品规格书

SPECIFICATION

CUSTOMER 客户： _____
PRODUCT 产品： _____ SAW FILTER _____
MODEL NO 型号： _____ HDBF09620A24 SMD-24 _____
PREPARED 编制： _____ CHECKED 审核： _____
APPROVED 批准： _____ DATE 日期： _____ 2010-7-21 _____

客户确认 CUSTOMER RECEIVED:		
审核 CHECKED	批准 APPROVED	日期 DATE

无锡市好达电子有限公司
Shoulder Electronics Limited

更改历史记录 History Record

更改日期 Date	规格书编号 Spec. No.	产品型号 Part No.	客户产品型号 Customer No.	更改内容描述 Modify Content	备注 Remark

1. SCOPE

This specification shall cover the characteristics of SAW filter with HDBF09620A24 used for the page system.

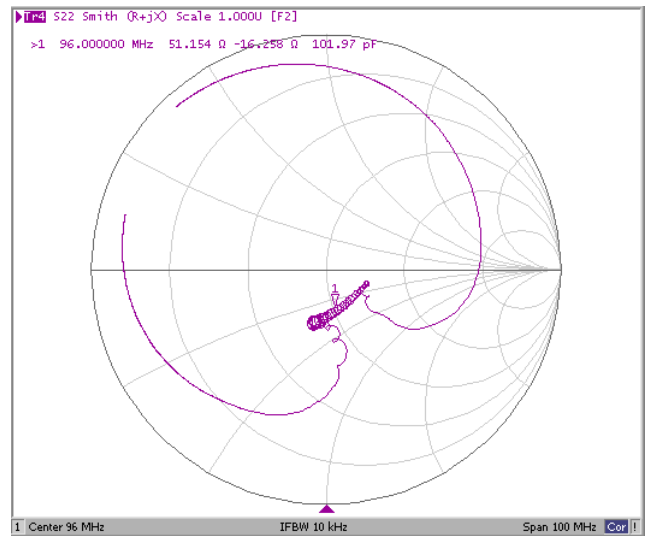
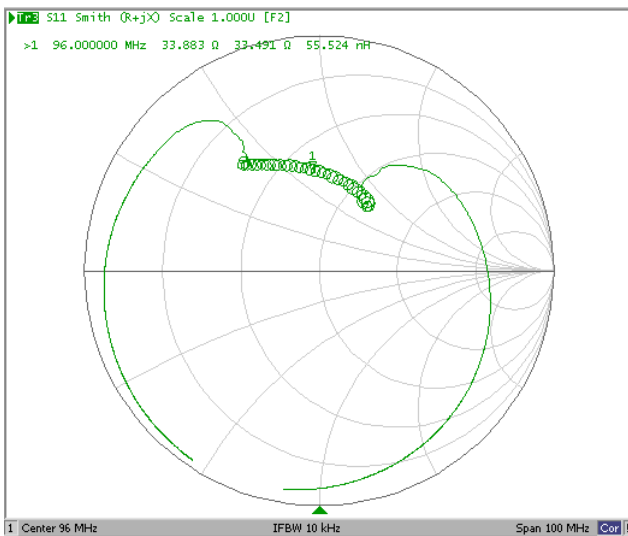
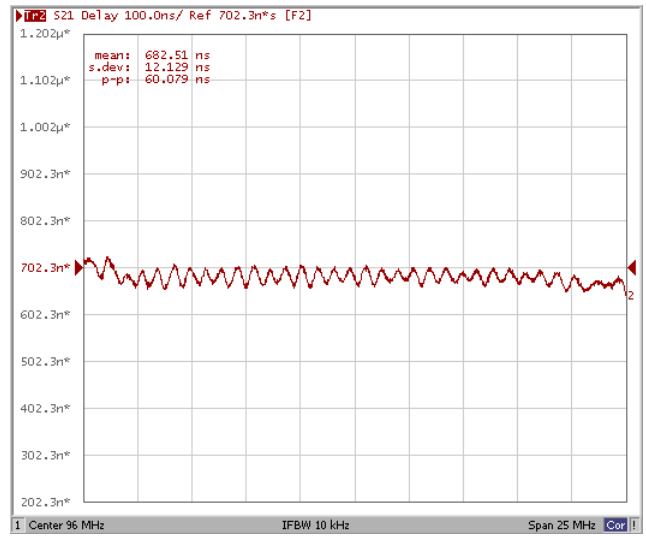
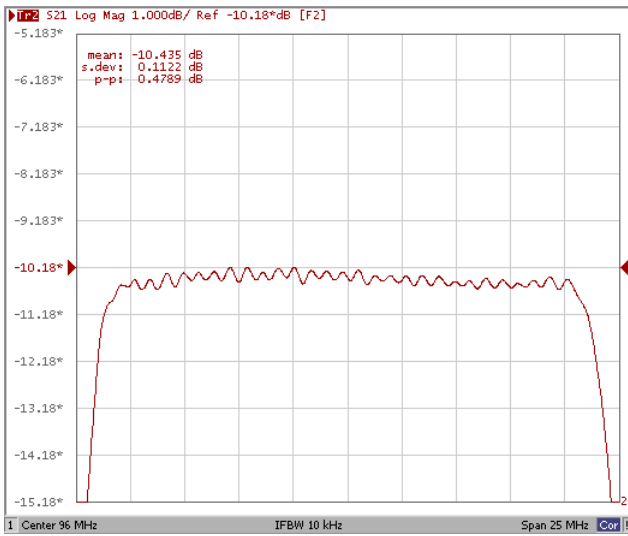
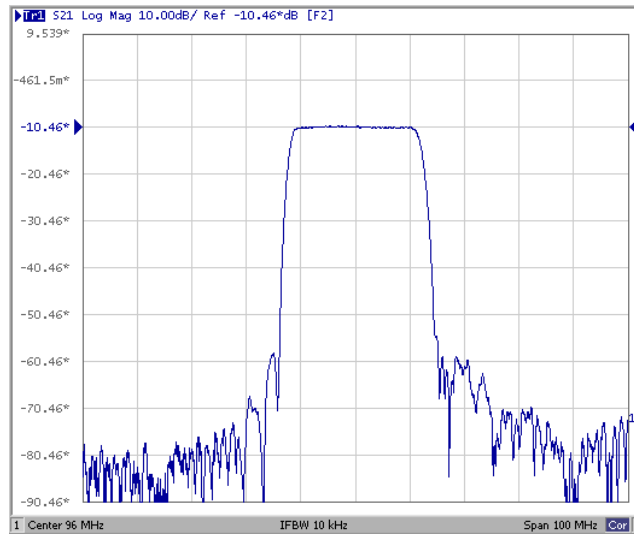
2. ELECTRICAL SPECIFICATION

Max.DC voltage between any 2 terminals	30VDC
Storage temperature range	-40°C to +85°C
Operation temperature range	-40°C to +85°C
Maximum Input Power	10dBm

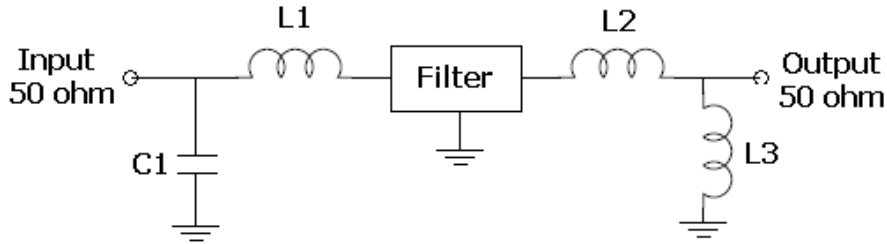
2.2 Electronic Characteristics

Item	Requirement			Unit
	Min.	Typical.	Max.	
Nominal center Frequency	-	96	-	MHz
Insertion loss (86.0MHz~106.0MHz)	-	9.5	12	dB
-1dB Bandwidth	-	22.0	-	MHz
-40dB Bandwidth	-	28.3	-	MHz
Relative attenuation				
0MHz ~68.4MHz	51	60		dB
76.8MHz	40	50	-	
123.6MHz~162.8MHz	56	63		
162.8MHz~1000MHz	35	45		
Amplitude ripple (86.0MHz~106.0MHz)		0.65	1.2	dB
Group delay ripple (86.0MHz~106.0MHz)		60	100	ns
Input IP3	35	45		dBm
VSWR		3		
Temperature Coefficient			-86	ppm/°C

Typical frequency response



3. TEST CIRCUIT

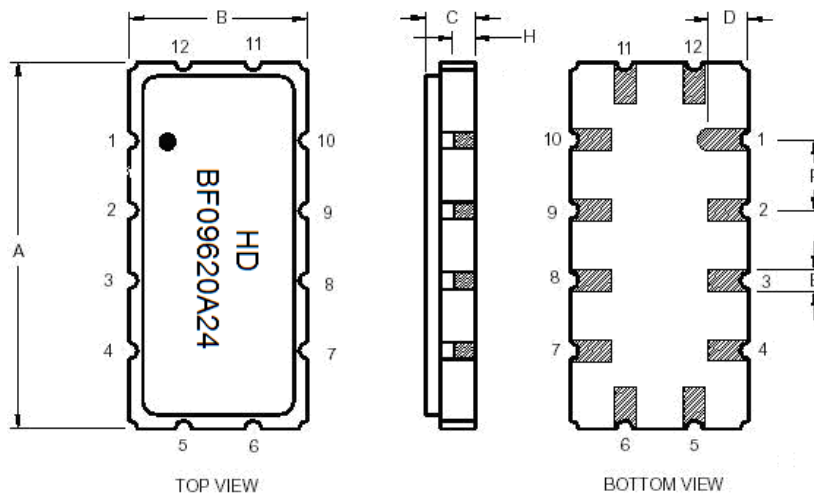


Input : L1 = 82 nH , C1 = 39 pF

Output : L2 = 27 nH , L3 =56 nH

(Notes: Component values may change depending on board layout)

4.DIMENSION



Dimension	mm		
	min	typ	max
A	13.1	13.3	13.5
B	6.3	6.5	6.7
C	1.21	1.36	1.51
D		1.5	
E		0.8	
H	0.72	0.76	0.80
P		2.54	

Pin Configuration	
11	Input
5	Output
Other	Ground

5. ENVIRONMENTAL CHARACTERISTICS

5-1 Temperature cycling

Subject the device to a low temperature of -40°C for 30 minutes. Following by a high temperature of $+25^{\circ}\text{C}$ for 5 Minutes and a higher temperature of $+85^{\circ}\text{C}$ for 30 Minutes. Then release the device into the room conditions for 1 to 2 hours prior to the measurement. It shall meet the specifications in 2.2.

5-2 Resistance to solder heat

Submerge the device terminals into the solder bath at $260^{\circ}\text{C} \pm 5^{\circ}\text{C}$ for 10 ± 1 sec. Then release the device into the room conditions for 4 hours. It shall meet the specifications in 2.2.

5-3 Solderability

Submerge the device terminals into the solder bath at $245^{\circ}\text{C} \pm 5^{\circ}\text{C}$ for 5s, More than 95% area of the soldering pad must be covered with new solder. It shall meet the specifications in 2.2.

5-4 Mechanical shock

Drop the device randomly onto the concrete floor from the height of 1 m 3 times. the filter shall fulfill the specifications in 2.2.

5-5 Vibration

Subject the device to the vibration for 2 hour each in x,y and z axes with the amplitude of 1.5 mm at 10 to 55 hz. The filter shall fulfill the specifications in 2.2.

6. REMARK

6.1 Static voltage

Static voltage between signal load & ground may cause deterioration & destruction of the component. Please avoid static voltage.

6.2 Ultrasonic cleaning

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning

6.3 Soldering

Only leads of component may be soldered. Please avoid soldering another part of component.